

Parker Chomerics CHO-BOND® 584-29 SYRINGE-PAK™ Silver Filled Conductive Epoxy and Hardener

Category : Polymer , Adhesive , Thermoset , Epoxy , Epoxy Adhesive

Material Notes:

Description: Chomerics CHO-BOND 584-29 is a two-component, highly conductive adhesive system that combines the strong adhesive characteristics of epoxy with the superior conductivity of pure silver. This new syringe system simplifies the mixing of resin and hardening components, and improves dispensing accuracy and efficiency. This result is less compound waste and lower applied cost. Features: Easy and efficient application system; Pure silver filler. Superior conductivity; 100% solids, no VOC's and Room temperature cure in 24 hours. Information provided by Chomerics

Order this product through the following link:

http://www.lookpolymers.com/polymer_Parker-Chomerics-CHO-BOND-584-29-SYRINGE-PAK-Silver-Filled-Conductive-Epoxy-and-Hardener.php

Physical Properties	Metric	English	Comments
Specific Gravity	2.20 g/cc	2.20 g/cc	ASTM D792

Mechanical Properties	Metric	English	Comments
Shear Strength	>= 8.27 MPa	>= 1200 psi	Lap; ASTM D1022

Electrical Properties	Metric	English	Comments
Volume Resistivity	0.0020 ohm-cm	0.0020 ohm-cm	Chomerics 95-40-5101 and 95-40-5102

Processing Properties	Metric	English	Comments
Cure Time	15.0 min	0.250 hour	
	@Temperature 113 °C	@Temperature 235 °F	
Shelf Life	9.00 Month	9.00 Month	
	@Temperature 24.0 °C	@Temperature 75.2 °F	

Descriptive Properties	Value	Comments
Filler	Ag	
Mix Ratio	0.069	
Work Life	0.5 hrs	

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